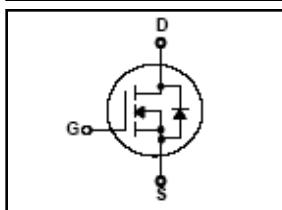


## HFS10N60U 600V N-Channel MOSFET

### FEATURES

- Originative New Design
- Superior Avalanche Rugged Technology
- Robust Gate Oxide Technology
- Very Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Unrivalled Gate Charge : 29 nC (Typ.)
- Extended Safe Operating Area
- Lower  $R_{DS(ON)}$  : 0.67 Ω (Typ.) @ $V_{GS}=10V$
- 100% Avalanche Tested

$BV_{DSS} = 600 V$   
 $R_{DS(on)\ typ} = 0.67 \Omega$   
 $I_D = 9.5 A$



### Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise specified

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-Source Voltage	600	V
$I_D$	Drain Current – Continuous ( $T_C = 25^\circ C$ )	9.5*	A
	Drain Current – Continuous ( $T_C = 100^\circ C$ )	6.0*	A
$I_{DM}$	Drain Current – Pulsed (Note 1)	38*	A
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	470	mJ
$I_{AR}$	Avalanche Current (Note 1)	9.5	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	5.0	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ C$ )	50	W
	- Derate above $25^\circ C$	0.40	W/ $^\circ C$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ C$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ C$

\* Drain current limited by maximum junction temperature

### Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	2.5	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	

## Package Marking and Ordering Information

Device Marking	Week Marking	Package	Packing	Quantity	RoHS Status
HFS10N60U	YWWX	TO-220F	Tube	50	Pb Free
HFS10N60U	YWWXg	TO-220F	Tube	50	Halogen Free

## Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### On Characteristics

$V_{GS}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	2.5	--	4.5	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}$ , $I_D = 4.75 \text{ A}$	--	0.67	0.8	$\Omega$

### Off Characteristics

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	600	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	0.6	--	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 600 \text{ V}$ , $V_{GS} = 0 \text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 480 \text{ V}$ , $T_C = 125^\circ\text{C}$	--	--	10	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	--	--	$\pm 100$	nA

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 25 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $f = 1.0 \text{ MHz}$	--	1600	2100	pF
$C_{oss}$	Output Capacitance		--	140	180	pF
$C_{rss}$	Reverse Transfer Capacitance		--	11	14.5	pF

### Switching Characteristics

$t_{d(on)}$	Turn-On Time	$V_{DS} = 300 \text{ V}$ , $I_D = 9.5 \text{ A}$ , $R_G = 25 \Omega$ (Note 4,5)	--	50	100	ns
$t_r$	Turn-On Rise Time		--	70	140	ns
$t_{d(off)}$	Turn-Off Delay Time		--	160	320	ns
$t_f$	Turn-Off Fall Time		--	60	120	ns
$Q_g$	Total Gate Charge	$V_{DS} = 480 \text{ V}$ , $I_D = 9.5 \text{ A}$ , $V_{GS} = 10 \text{ V}$ (Note 4,5)	--	29	38	nC
$Q_{qs}$	Gate-Source Charge		--	8.5	--	nC
$Q_{qd}$	Gate-Drain Charge		--	9	--	nC

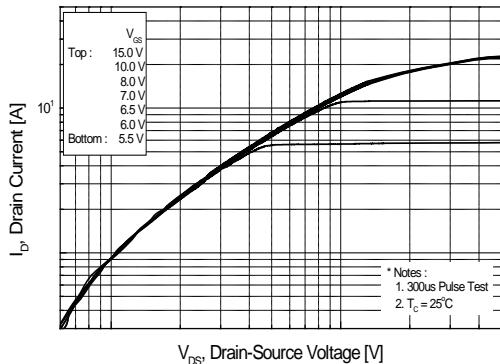
### Source-Drain Diode Maximum Ratings and Characteristics

$I_S$	Continuous Source-Drain Diode Forward Current	--	--	9.5	A	
$I_{SM}$	Pulsed Source-Drain Diode Forward Current	--	--	38		
$V_{SD}$	Source-Drain Diode Forward Voltage	$I_S = 9.5 \text{ A}$ , $V_{GS} = 0 \text{ V}$	--	--	1.4	V
$trr$	Reverse Recovery Time	$I_S = 9.5 \text{ A}$ , $V_{GS} = 0 \text{ V}$ $dI/dt = 100 \text{ A}/\mu\text{s}$ (Note 4)	--	340	--	ns
$Qrr$	Reverse Recovery Charge		--	3.3	--	$\mu\text{C}$

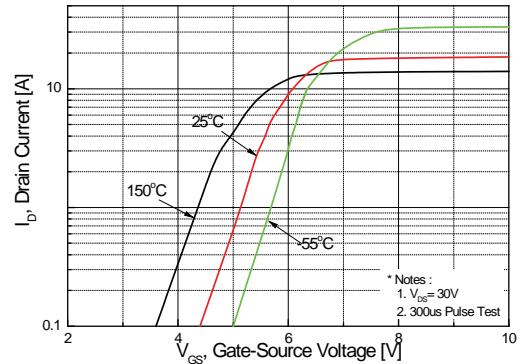
#### Notes :

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L=9.6\text{mH}$ ,  $I_{AS}=9.5\text{A}$ ,  $V_{DD}=50\text{V}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3.  $I_{SD}\leq 9.5\text{A}$ ,  $di/dt\leq 200\text{A}/\mu\text{s}$ ,  $V_{DD}\leq BV_{DSS}$ , Starting  $T_J=25^\circ\text{C}$
4. Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$
5. Essentially Independent of Operating Temperature

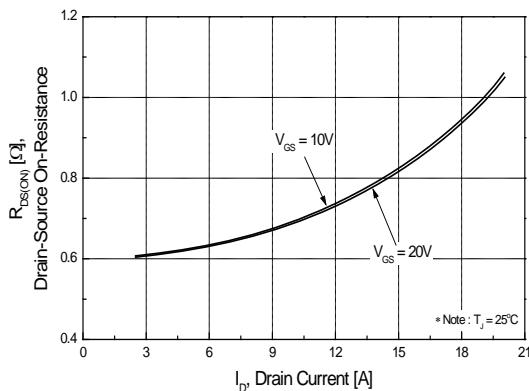
## Typical Characteristics



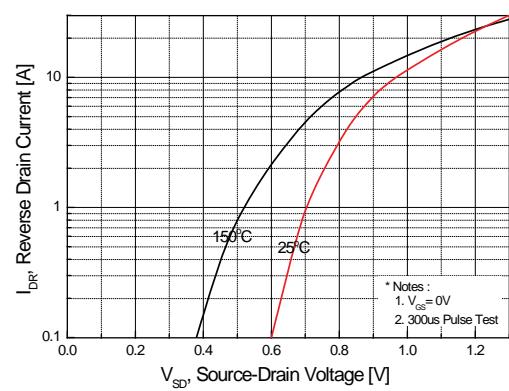
**Figure 1. On Region Characteristics**



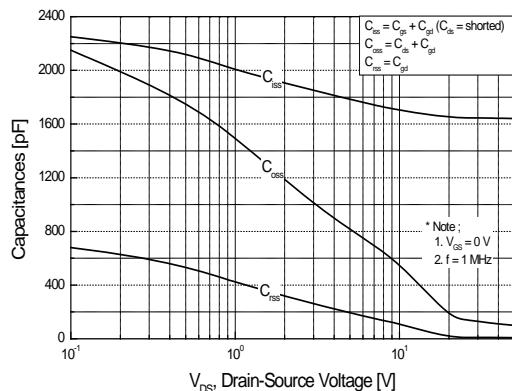
**Figure 2. Transfer Characteristics**



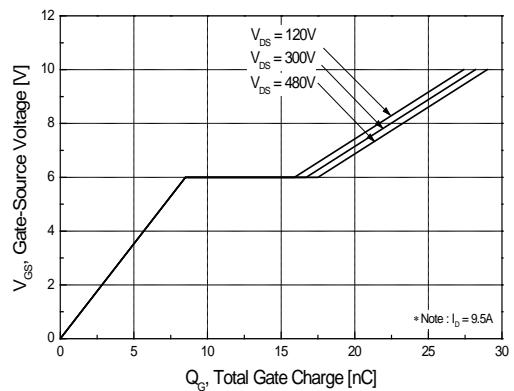
**Figure 3. On Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

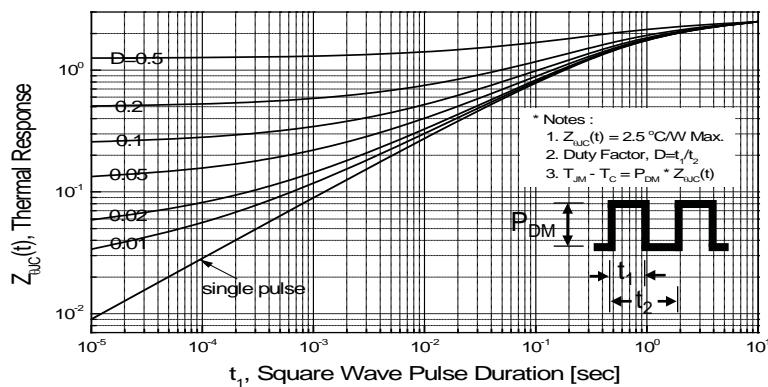
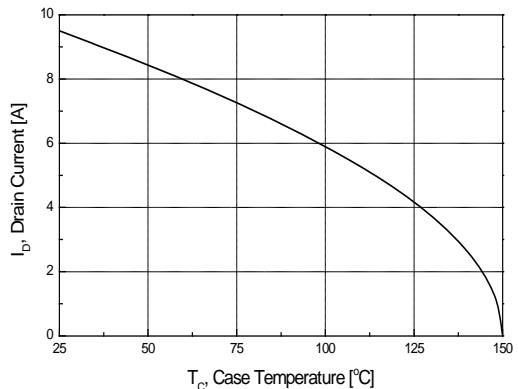
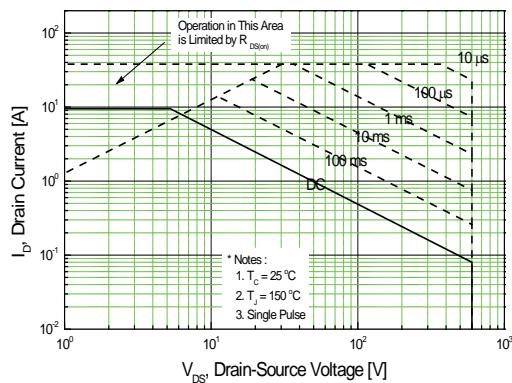
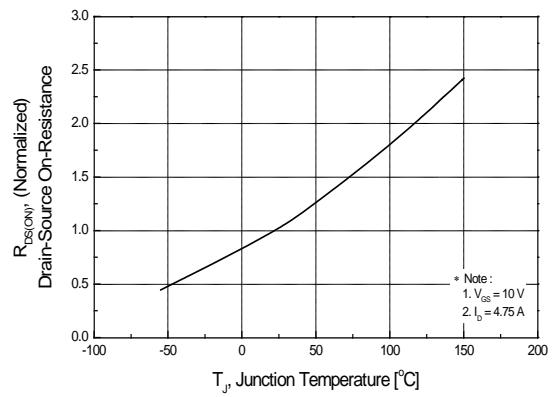
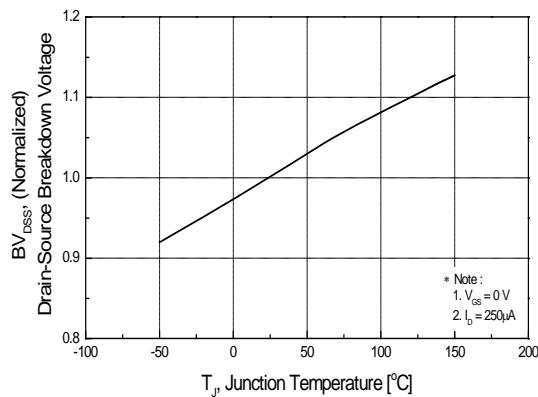


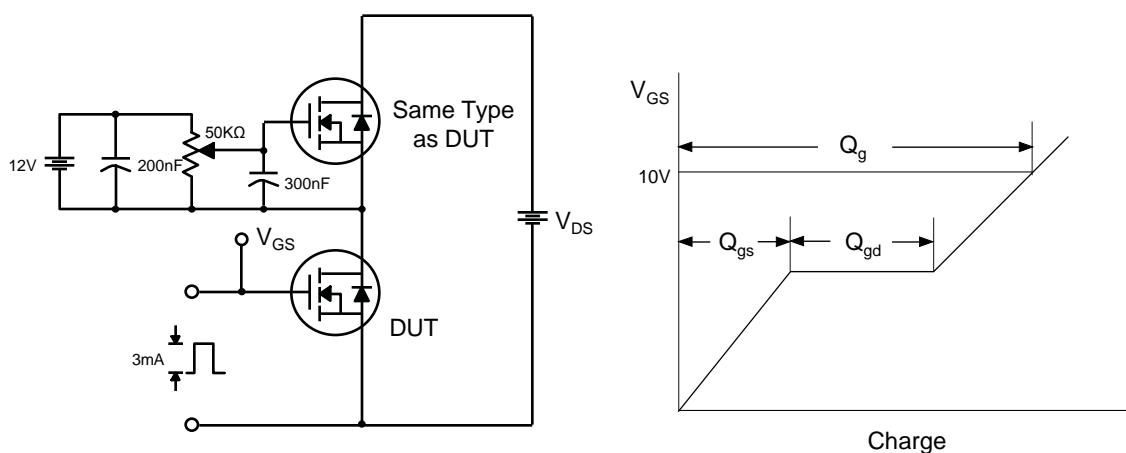
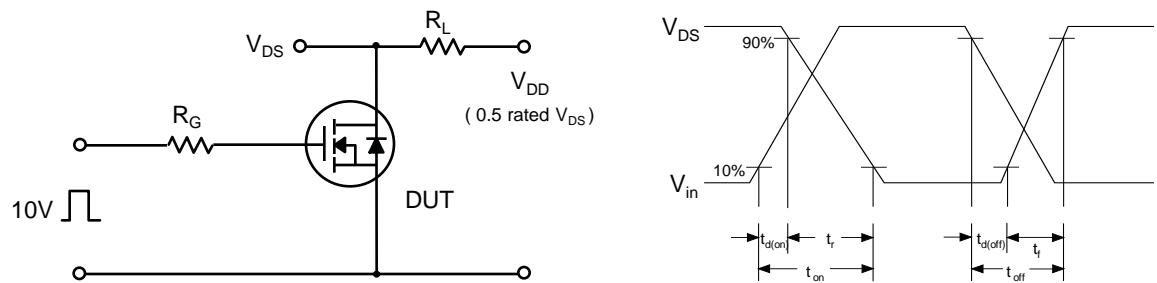
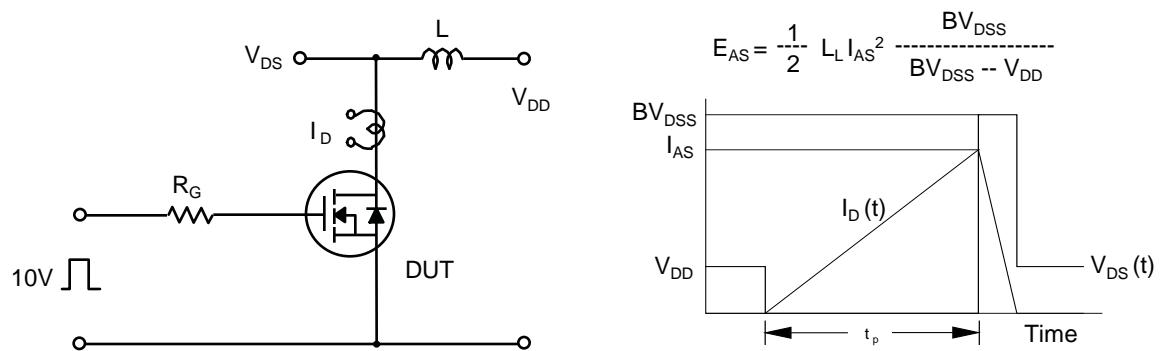
**Figure 5. Capacitance Characteristics**

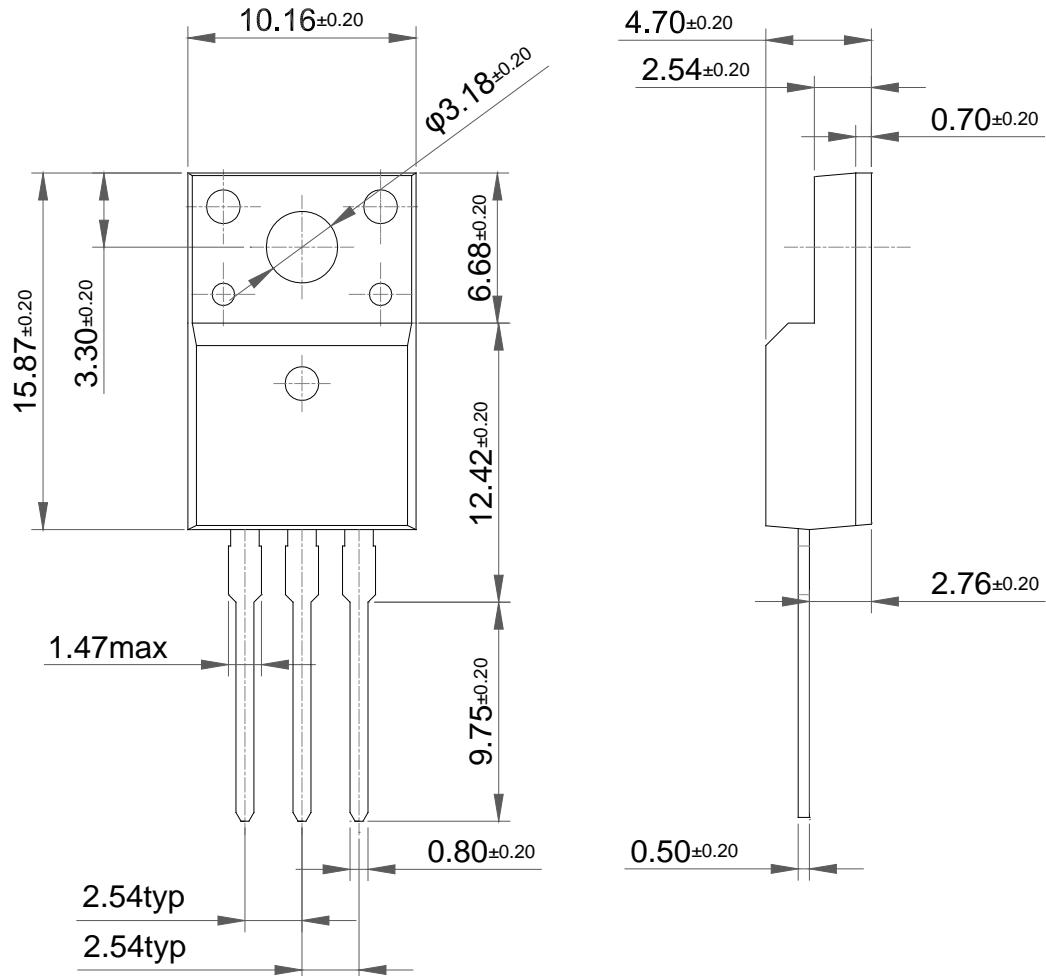


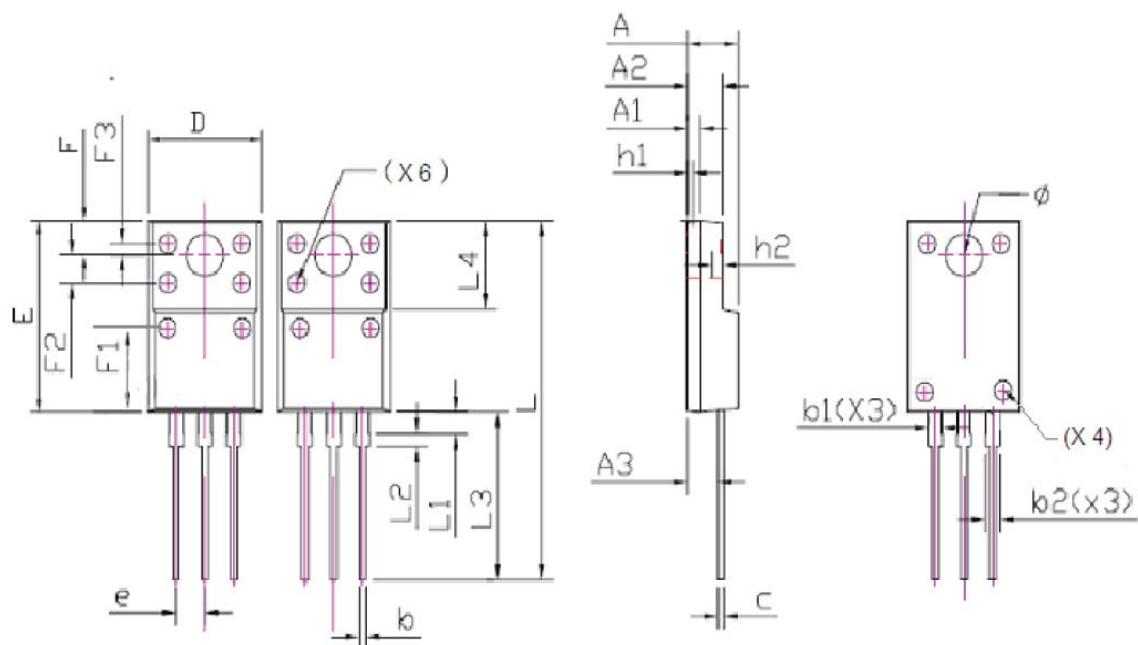
**Figure 6. Gate Charge Characteristics**

## Typical Characteristics



**Fig 12. Gate Charge Test Circuit & Waveform****Fig 13. Resistive Switching Test Circuit & Waveforms****Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms**

**Package Dimension****TO-220F (A)**

**Package Dimension****TO-220F (B)**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
A1	1.300	REF.	0.051	REF.
A2	2.800	3.300	0.110	0.130
A3	2.500	2.900	0.098	0.114
b	0.500	0.750	0.020	0.030
b1	1.150	1.300	0.045	0.051
b2	1.150	1.400	0.045	0.055
c	0.500	0.750	0.020	0.030
D	9.900	10.360	0.390	0.408
E	14.800	15.200	0.583	0.598
e	2.540	TYP.	0.100	TYP.
F	2.700	REF.	0.106	REF.
F1	6.300	REF.	0.248	REF.
F2	2.200	REF.	0.087	REF.
F3	0.900	REF.	0.035	REF.
Φ	3.200	3.500	0.126	0.138
h1	0.500	REF.	0.020	REF.
h2	0.800	REF.	0.031	REF.
L	28.000	29.000	1.102	1.142
L1	1.400	1.800	0.055	0.071
L2	1.200	2.000	0.047	0.079
L3	13.0	13.8	0.512	0.543
L4	7.000	REF.	0.276	REF.